NEWS RELEASE

SCREEN
DAINIPPON SCREEN MFG. CO., LTD.

Doc. No.: NR061116-3E

November 16, 2006

New production factory for semiconductor manufacturing equipment completed

Built to meet increased demand for wafer cleaning equipment

The Semiconductor Equipment Company (President: Takashige Suetake) of Dainippon Screen Mfg. Co., Ltd. (Headquarters: Kyoto, Japan) has recently completed construction of a new semiconductor equipment factory known as Fab.FC-2 within SCREEN's existing Hikone plant (480-1 Takamiya-Cho, Hikone, Shiga), after breaking ground in April 2006. The factory will commence operations tomorrow.

The continued expansion of the market for consumer electronics such as digital appliances and memory cards is complemented by increasing demand for personal computers and cellular phones in emerging countries. All this is helping to maintain the growth of the semiconductor industry, and levels of manufacturing plant investment among major semiconductor device manufacturers are expected to remain high as a result. Makers of manufacturing equipment for the semiconductor industry are faced with an urgent need to establish production systems that will be able to accommodate the increasing demand.

The new Fab.FC-2 factory, the Screen Group's fourth semiconductor equipment manufacturing factory, is designed to meet the growing needs of the semiconductor industry by increasing SCREEN's manufacturing capacity for batch and other wafer cleaning equipment. Paired with Fab.FC-1, a factory constructed within the same Hikone site in 2001, Fab.FC-2 will double SCREEN's production capacity and enable long-term, stable supply to semiconductor device manufacturers, ensuring their continuing prosperity. This new, cutting-edge factory also features a clean room suitable for forthcoming needs, including the production of manufacturing equipment for the 450 mm size wafers that are expected to become a semiconductor fabrication standard in the future.

The construction of the Fab.FC-2 factory has expanded SCREEN's production capacity, allowing it to meet the increasing demand for batch and other wafer cleaning equipment. It is also expected to improve SCREEN's competitiveness and help the company further increase its market share in the semiconductor equipment industry.

Fab.FC-2
Please download the photo from
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New Factory Overview

Name:	Hikone Plant Fab.FC-2 “Fab.” stands for Fabulous and Fabricate and “FC” is Fine Cleaning, which is used in the product label for the FC-3100 300 millimeter wafer cleaning unit. SCREEN is working towards next-generation implementation of production management control that utilizes information technology (IT).
Location:	480-1 Takamiya-cho, Hikone, Shiga
Size of Site:	Approximately 5,600 square meters (The total area of the Hikone plant is approximately 144,300 square meters)
Building Footprint:	Approximately 5,200 square meters
Floor Space:	Approximately 9,000 square meters
Building Type:	Steel reinforced structure, 3 floors
Cost:	Approximately 3.0 billion yen
Completion:	November 2006
Intended Use:	Production of wafer cleaning equipment (batch type cleaning equipment, single-wafer cleaning equipment, etc.)